

PAT-NO: JP411140144A

DOCUMENT-IDENTIFIER: JP 11140144 A

TITLE: RESIN COMPOSITION AND CURED
PRODUCT THEREOF

PUBN-DATE: May 25, 1999

INVENTOR-INFORMATION:

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ASSIGNEE-INFORMATION:

NAME	COUNTRY
NIPPON KAYAKU CO LTD	N/A

APPL-NO: JP09316649

APPL-DATE: November 4, 1997

INT-CL (IPC): C08F290/06 , C08F020/30 , C08F299/02 , C08G059/14 ,
C08G059/17 , G03F007/027 , G03F007/038 ,
H05K003/18 , H05K003/28

ABSTRACT:

PROBLEM TO BE SOLVED: To provide a resin compsn. and a cured product thereof which can be easily developed, possess excellent solvent resistance and plating solution resistance, possess heat resistance high enough to withstand soldering temps., and are particularly suitable for permanent resists of printed wiring boards.

SOLUTION: This resin compsn. and a cured product thereof comprise: an

epoxy (meth)acrylate resin obtd. by reacting an epoxy resin represented by the formula (where (n) is an average value and is an no. of 0 or more) with a monocarboxylic acid contg. an unsatd. group; and a diluent.

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